Editorial

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Welcome to Volume 1, Number 3 of IMAPS’ Journal of Microelectronics and Electronic Packaging.

I am pleased to announce the addition of the following as Associate Editors to the Journal’s Advisory Board: Dr. Aicha Elshabini from the University of Arkansas, Dr. Nihal Sinnadurai from the U.K., and Dr. Zhongmin Xiao from the Nanyang Technical University, Singapore. Our Advisory Board now consists of members from the USA, Asia and the EU!

We have recently received our International Standard Serial Number (ISSN) from the Library of Congress (U.S.) and this enhances the archival status of our Journal.

Considering the relentless progress made towards both miniaturization of features within semiconductors and also increasing their power-speed factor, it is not surprising that researchers are interested in examining the various aspects involved in cooling such semiconductor devices and the products that use them. As such, seven of the nine papers in this issue cover a wide spectrum of cooling techniques, processing temperatures, etc. So, prepare yourself for a whirlwind of convective flows characterized by Reynolds, Rayleigh, Prandlt and Nusselt numbers!

Starting with this issue we are reintroducing a section titled "Invited Manuscript (Best Paper – IMAPS Symposia)" highlighting papers that have earned "Best of Symposium" or "Best of Session" awards at a recent IMAPS symposium.

Regards,

Delip “Doug” Bokil
Editor-in-Chief